



Material Content Data Sheet



Sales Product Name		TLD5097EP		Issued		13. August 2019		
MA#		MA005354095						
Package		PG-TSDSO-14-3		Weight*		61.20 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.131	3.48	3.48	34828	34828
leadframe	inorganic material	phosphorus	7723-14-0	0.008	0.01		135	
	non noble metal	zinc	7440-66-6	0.033	0.05		541	
	non noble metal	iron	7439-89-6	0.662	1.08		10812	
wire	non noble metal	copper	7440-50-8	26.866	43.92	45.06	439005	450493
	non noble metal	copper	7440-50-8	0.158	0.26	0.26	2590	2590
	encapsulation	organic material	carbon black	1333-86-4	0.087	0.14		1422
encapsulation	plastics	epoxy resin	-	3.393	5.54		55443	
	inorganic material	silicondioxide	60676-86-0	25.520	41.70	47.38	417004	473869
leadfinish	non noble metal	tin	7440-31-5	1.451	2.37	2.37	23707	23707
plating	noble metal	silver	7440-22-4	0.160	0.26	0.26	2610	2610
glue	plastics	epoxy resin	-	0.182	0.30		2976	
	noble metal	silver	7440-22-4	0.546	0.89	1.19	8927	11903
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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